TOSHIBA LED LAMP GaP RED LIGHT EMISSION

# TLR1002(ZD)

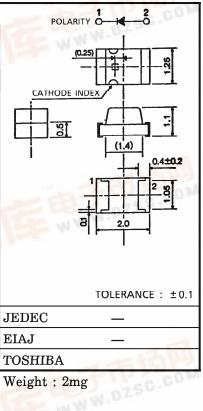
LED SURFACE MOUNT DEVICE

Unit in mm

- 2.0 (L)×1.25 (W)×1.1 (H) mm Size Small Package-High Density Mounting is Available
- Available of Automounting Machine Use
- Reflow Soldering is Applicable
- Low Drive Current (10 $\mu$ A), Stable Forward Voltage (1.65V) Recommended Forward Current :  $I_F = 10 \mu A$  (DC)
- Applications: Solar Battery Equipment etc.

#### MAXIMUM RATINGS ( $Ta = 25^{\circ}C$ )

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	$I_{\mathbf{F}}$	25	mA
Reverse Voltage	$v_{R}$	4	V
Power Dissipation	$P_{\mathbf{D}}$	70	mW
Operating Temperature Range	$T_{ m opr}$	-25~80	°C
Storage Temperature Range	$T_{ m stg}$	-30~85	°C



Weight: 2mg

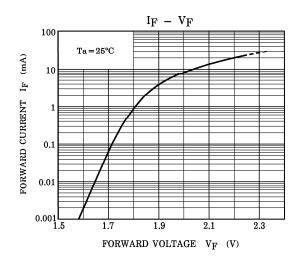
#### ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

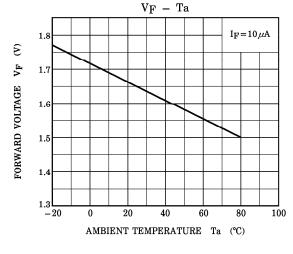
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	$V_{\mathbf{F}}$	$I_{\mathbf{F}} = 10 \mu A$	1.53	1.65	1.73	V
	$V_{ m F}$	I <sub>F</sub> =1mA	1.7	1.8	1.9	V
Reverse Current	$I_{\mathbf{R}}$	$V_R=4V$		_	5	$\mu$ A
Luminous Intensity	$I_{ m V}$	I <sub>F</sub> =10mA		0.8		mcd
Peak Emission Wave Length	$\lambda_{\mathbf{P}}$	I <sub>F</sub> =10mA	_	700	_	nm
Spectral Line Half Width	Δλ	$I_F = 10 \text{mA}$	_	100	441	nm
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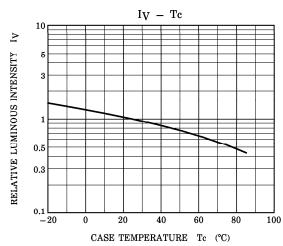
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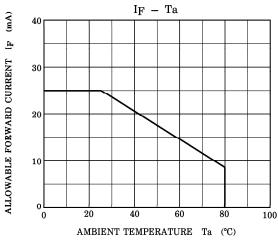
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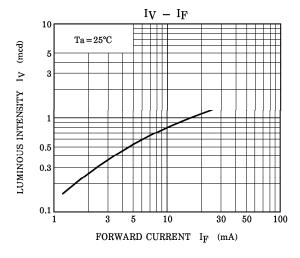
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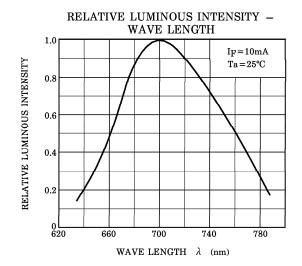






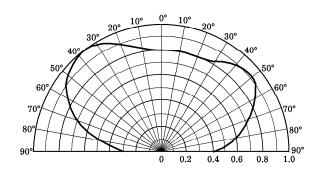






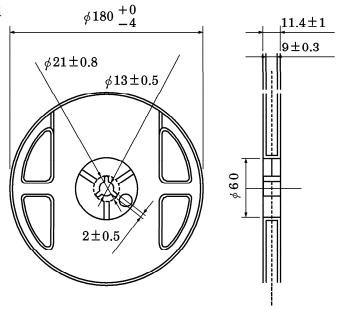
### RADIATION PATTERN

 $Ta = 25^{\circ}C$ 

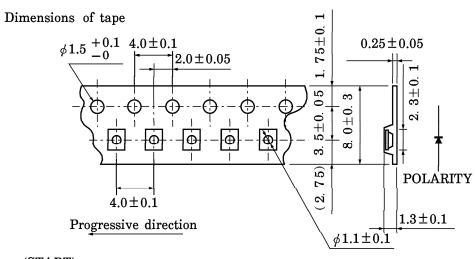


## TAPING SPECIFICATIONS:

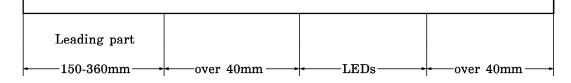
Dimensions of reel



Unit: mm



(START) (END)



Loaded quantity per reel

3000pcs

Packaging These LED devices are packed in an aluminum envelope with

silica-gel to avoid moisture absorption. The optical

characteristics may be affected by exposure to moisture in the air prior to soldering and storage at the following condition is

recommended:

Temperature : 5~30°C

Relative Humidity: 60% Maximum

Baking is required if the devices have been stored unopened for more than 6 months or if the aluminum envelope has been

opened for more than 1 week.

Recommended baking condition is  $60^{\circ}\text{C}$  for more than 12

hours

Precaution for mounting Do not apply force to the plastic part of the LED in high

temperature conditions.

Do not apply friction using a hard object or surface to avoid

injuring the plastic part of the LED.

Avoid contact between the LED and any other parts when

assembling the components into board.

#### **SOLDERING**

### Reflow soldering

- \* It is recommended to use a reflow furnace of the upper and lower heater type.
- \* The temperature profile as shown Fig.1 is recommended for soldering LEDs by the reflow furnace.

#### Temperature profile

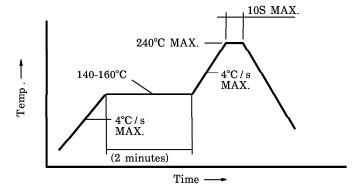
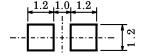


Fig.1

### Recommended soldering pattern



## Recommendations for manual soldering:

Soldering iron : Less than 25W
Temperature : Lower than 300°C
Time : Within 3 seconds

## Post solder cleaning:

When cleaning after soldering is needed, the following condition must be adhered to.

Cleaning solvents: AK225 or Alcohol

Temperature : 50°C (112°F) max. for 30 seconds or

30°C (86°F) max. for 3 minutes max.

Ultrasonic : 300W max.